

Amendments under PCT Art.34

1. (amended) A circuit board device for an information apparatus comprising:

5 a base board having mounted thereupon a plurality of low-frequency electronic components; and

a multilayer module board mounted at one surface of the base board and having mounted thereupon a plurality of high-frequency electronic components including at least a CPU and a memory, wherein:

10 at the multilayer module board which is a multilayered board smaller in size than the base board, the plurality of high-frequency electronic components are wired to one another through a wiring pattern at an inner layer.

2. (amended) A circuit board device for an information apparatus according to claim 1, wherein:

at least a graphics circuit in addition to the CPU and the memory, is mounted at the multilayer module board; and

at least a power circuit, a gyro and a GPS circuit are mounted at the base board.

20 3. (amended) A navigation system comprising a circuit board device for an information apparatus according to claim 1 or claim 2.

25 4. (amended) A circuit board achieved by mounting a multilayer module board according to claim 2 at a base board according to claim 2, wherein:

Art 34 Audit

the multilayer module board is a low-end module board, a high-speed module board that operates at higher speed than the low-end module board or an advanced function module board having more functions than the low-end module board; and

5 the base board is used commonly in conjunction with the low-end module board, the high-speed module board and the advanced function module board.

5. (amended) A multilayer module board used in a circuit board according to claim 4, comprising:

10 a plurality of high-frequency electronic components including a CPU and a memory mounted at, at least, a surface thereof, wherein:

the plurality of high-frequency electronic components are connected with one another through a wiring patterns formed at an inner layer thereof.

15 6. (amended) A multilayer module board according to claim 5, assuming an overall shape of a rectangle and having connector terminals provided as separate members each soldered onto one of four peripheral edges thereof.

20 7. (amended) A multilayer module board according to claim 6, wherein:

the four connector terminals each include a narrow, elongated base portion constituted of resin and a plurality of pins fixed to the base portion; and

the four connector terminals are each carried with the base portion attached to a transfer adapter and the four connector terminals are connected through soldering onto a rear surface of the board while attached to the transfer
5 adapter.

8. (amended) A multilayer module board according to claim 6, wherein:

the four connector terminals each include;
a narrow, elongated base portion constituted of resin;
10 a plurality of pins fixed to the base portion;
aligning pins projecting at both ends of the base portion to be used when soldering the connector terminal onto a rear surface of the board; and

15 inclined surfaces for position control formed at both ends of the base portion to be used when soldering the connector terminal;

a pair of positioning holes at which the aligning pins are loosely fitted are formed at each of four corners of the board; and

20 positions of the connector terminals are controlled when soldering the connector terminals as the inclined surfaces for position control at adjacent connector terminals come into contact with each other while the aligning pins are loosely fitted at the positioning holes.

9. (amended) A multilayer module board comprising:
a plurality of high-frequency electronic components
including a CPU and a memory mounted at, at least, a surface
thereof, wherein:

5 the plurality of high-frequency electronic components
are connected with one another through a wiring pattern
formed at an inner layer thereof;

the multilayer module board assumes an overall shape
of a rectangle and has connector terminals provided as
10 separate members each soldered onto one of four peripheral
edges thereof;

the four connector terminals each include a narrow,
elongated base portion constituted of resin and a plurality
of pins fixed to the base portion; and

15 after the four connector terminals are each carried
with the base portion attached to a transfer adapter, the four
connector terminals are connected through soldering onto a
rear surface of the board while attached to the transfer
adapter.

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10. (amended) A multilayer module board comprising:
a plurality of high-frequency electronic components
including a CPU and a memory mounted at, at least, one surface
thereof, wherein:

ART 31 AMDT

the plurality of high-frequency electronic components are connected with one another through a wiring pattern formed at an inner layer thereof;

the multilayer module board assumes an overall shape 5 of a rectangle and has connector terminals provided as separate members each soldered onto one of four peripheral edges thereof;

the four connector terminals each include;
a narrow, elongated base portion constituted of resin;
10 a plurality of pins fixed to the base portion;
aligning pins projecting at both ends of the base portion to be used when soldering the connector terminal onto a rear surface of the board; and

inclined surfaces for position control formed at both 15 ends of the base portion to be used when soldering the connector terminal;

a pair of positioning holes at which the aligning pins are loosely fitted are formed at each of four corners of the board; and

20 positions of the connector terminals are controlled when soldering the connector terminals as the inclined surfaces for position control at adjacent connector terminals come into contact with each other while the positioning pins are loosely fitted at the positioning holes.

11. (deleted)

12. (deleted)

13. (deleted)

APR 24 AMDT